

Zero outgassing and flux residue compatible underfill

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YINCAE
YINCAE Advanced Materials, LLC

Outline

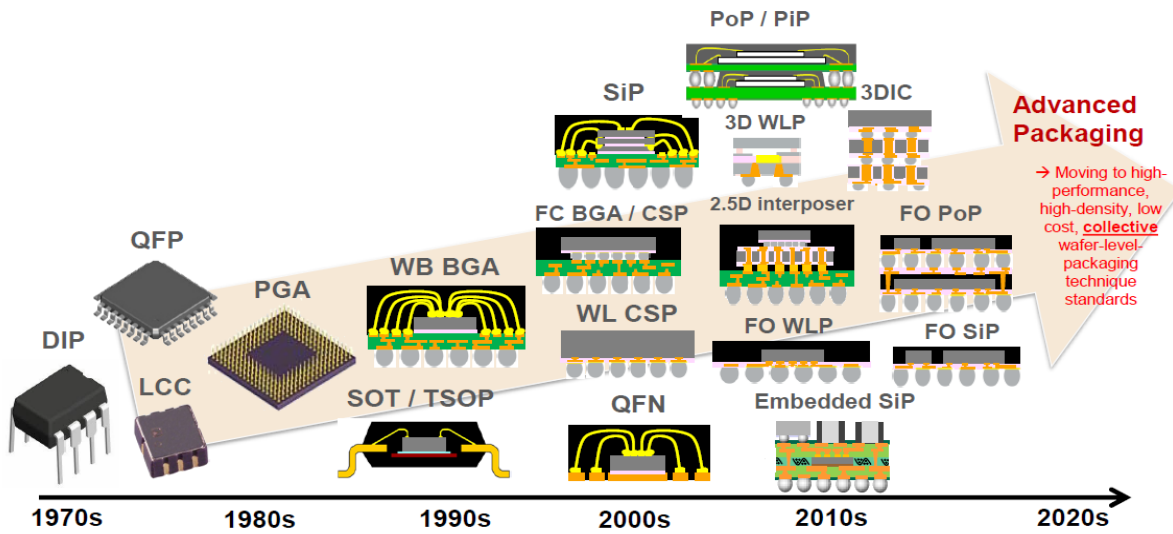
- Introduction
- Experiment
- Test and Reliability
- Discussion
- Conclusion

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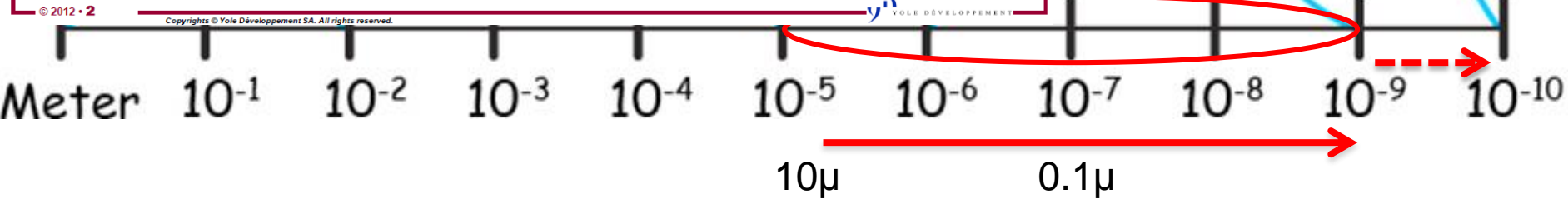
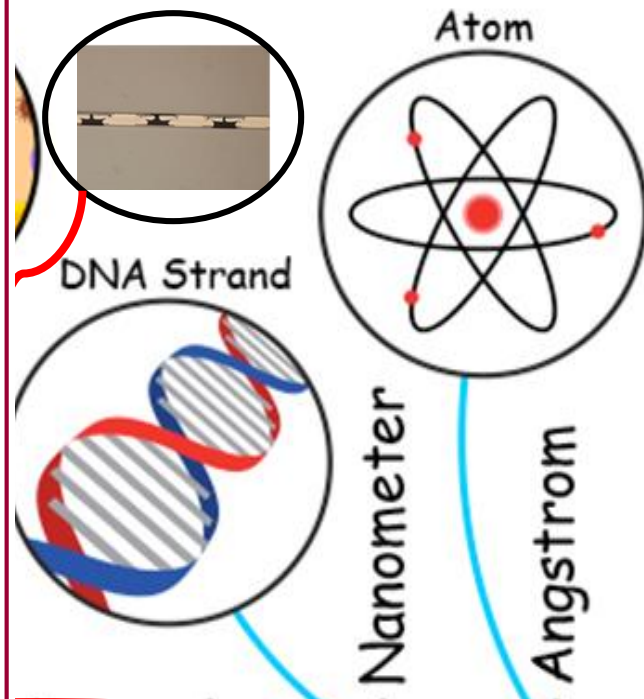
Miniaturization

Semiconductor chip packaging market evolution

- The pace of innovation in chip packaging industry has never been faster!
 → Today driven by semiconductor company giants (Intel, Samsung, TI, STMicro, TSMC, Qualcomm...) along with "Top 5" biggest packaging subcontractors (ASE, Amkor, SPIL, STATschippac, PTI...)



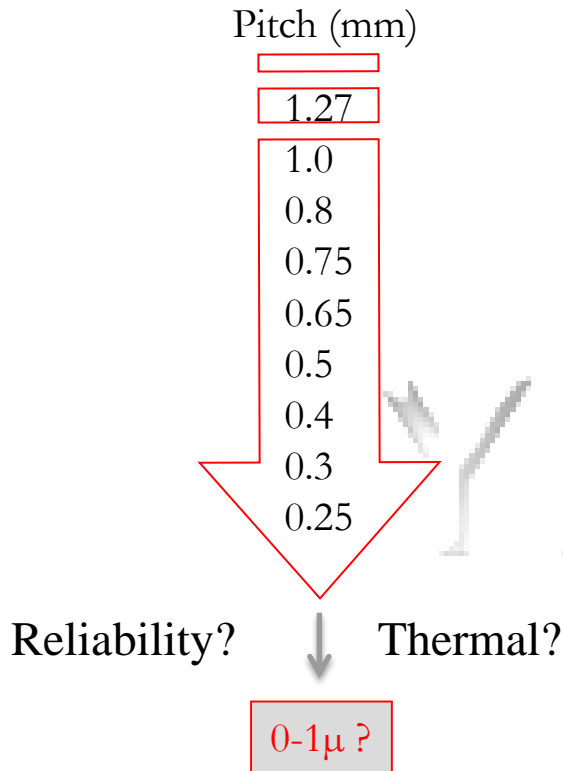
3D Interconnects



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YOLE DEVELOPPEMENT

Material's Challenging



■ Process Challenging:

a. Equipment tools

b. Assembly issue

c. **Materials** →

- Application Process
- Warpage
- Outgassing
- Flux residue

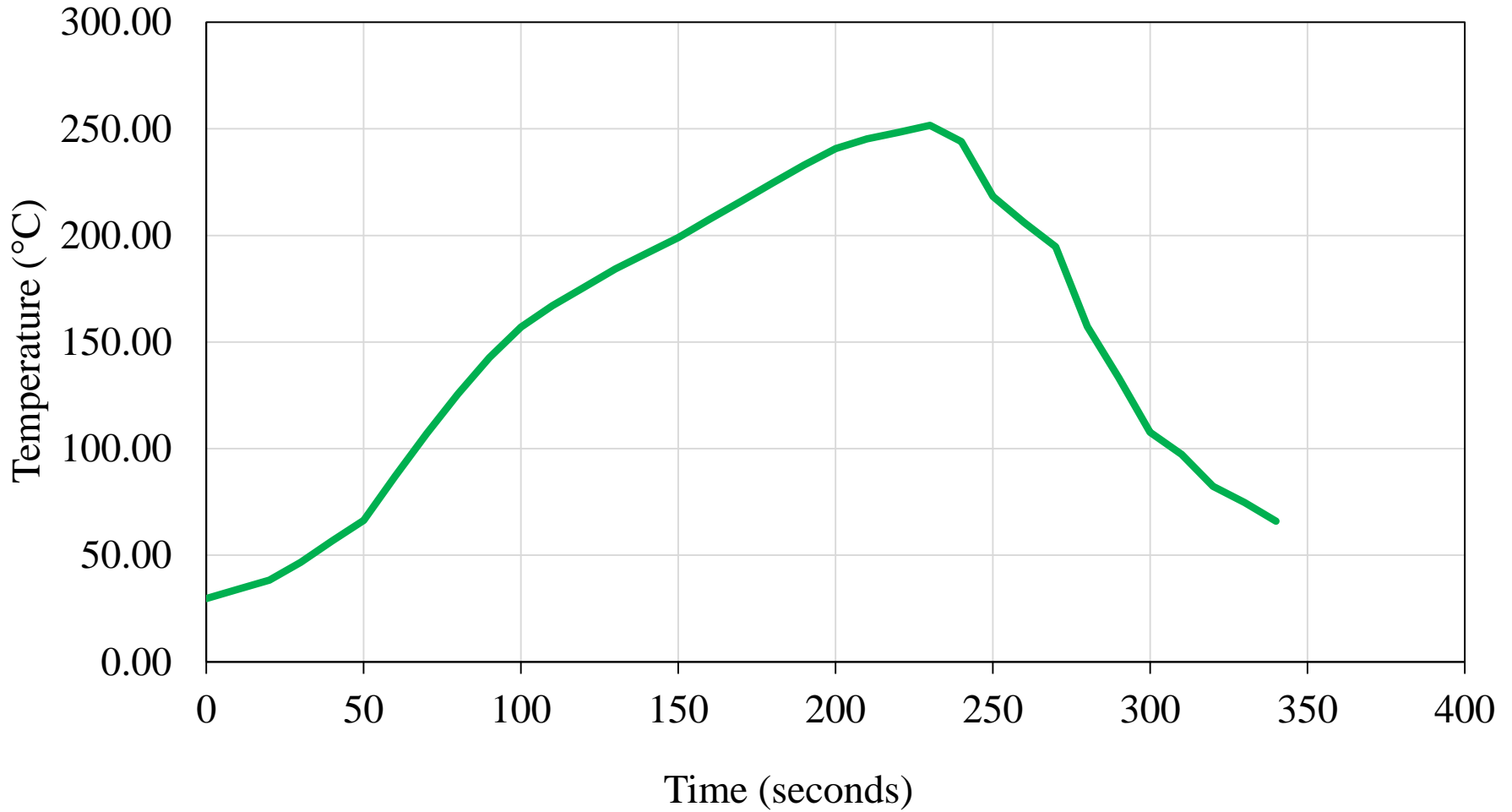
■ Reliability Challenging:

Experiments

- Reflow Profile
- Flowability Test
- Weight Loss Test
- Flux Compatibility Test
- Reliability Test

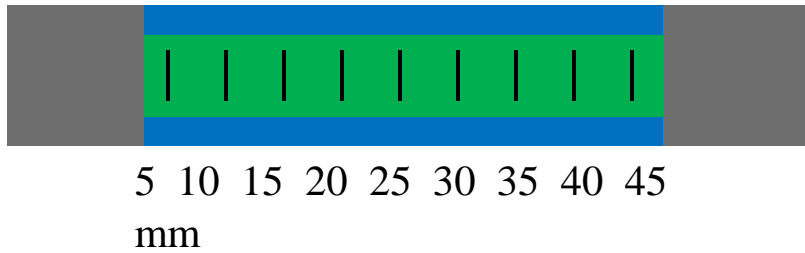
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Reflow Profile

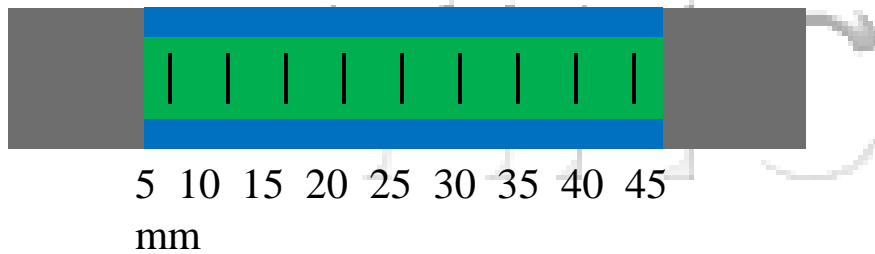


Flow Test Method

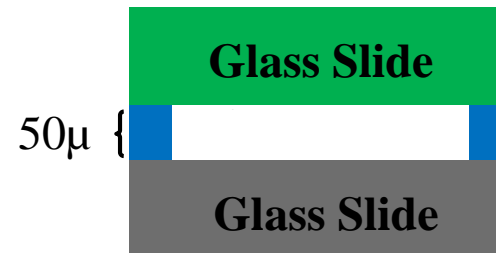
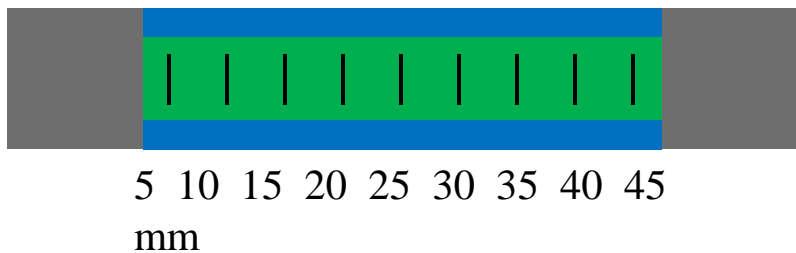
Apparatus 1



Apparatus 2



Apparatus 3

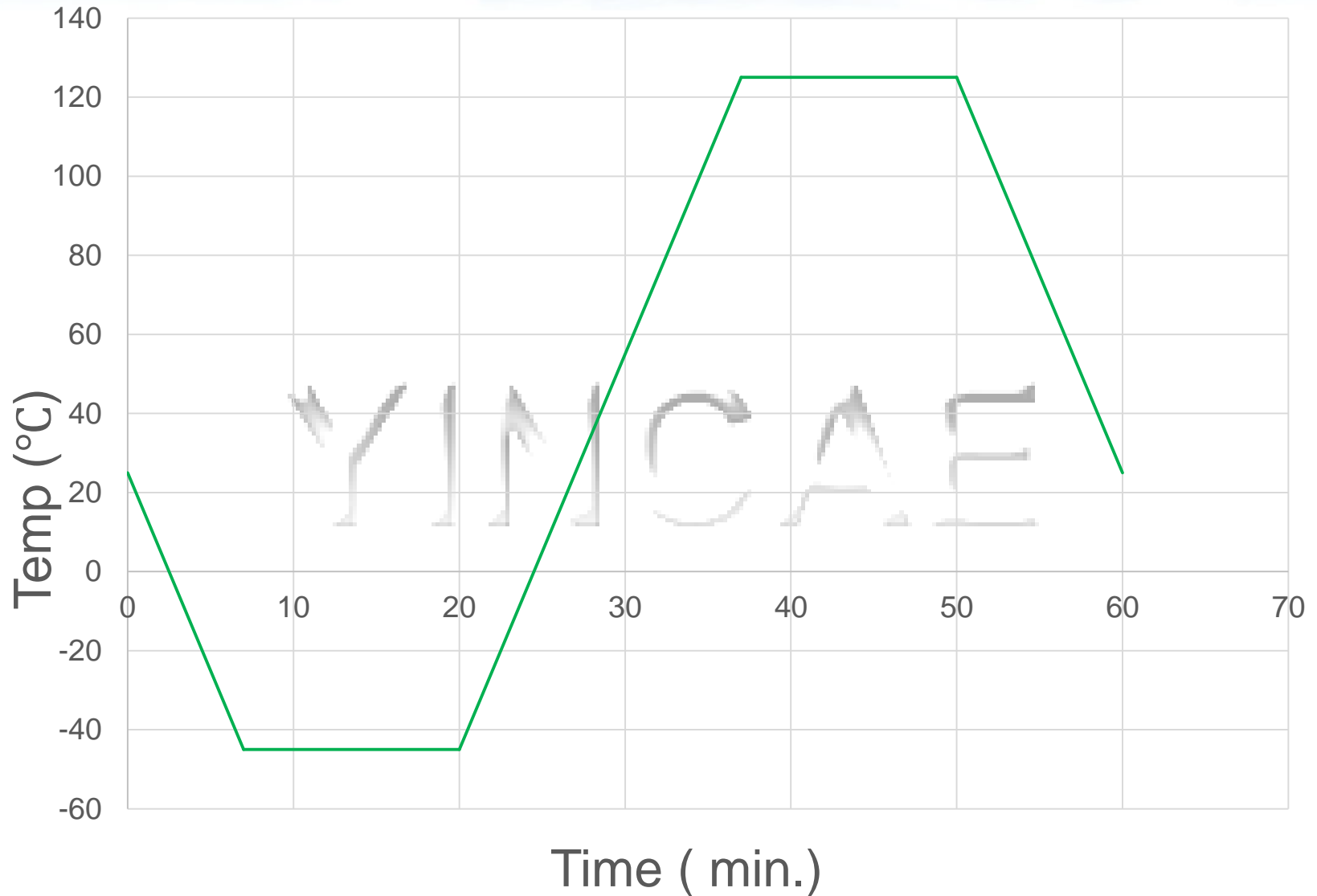


Weight Loss Measurement

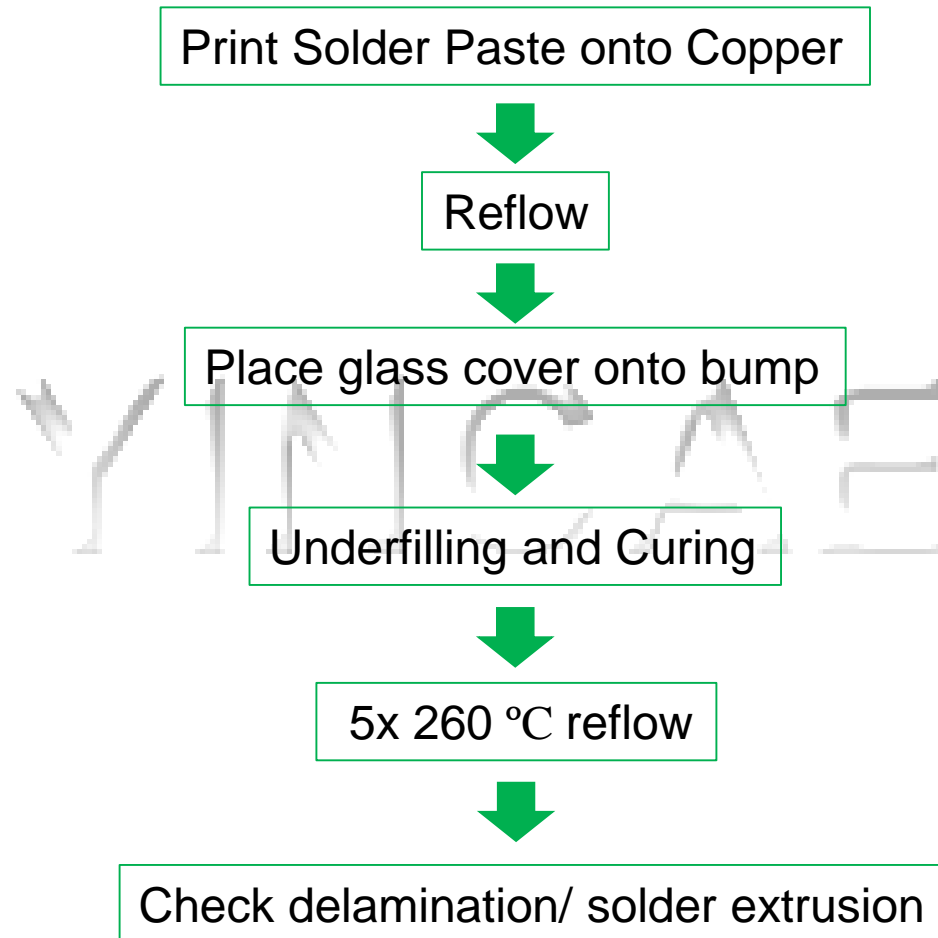
- Clean glass slide and dry
- Dispense 0.2 g underfill onto glass slide
- Reflow the glass with underfill using lead free reflow process
- Weigh the cured underfill after reflow

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Thermal Cycling Test



Flux Residue Compatibility Test



Test and Reliability

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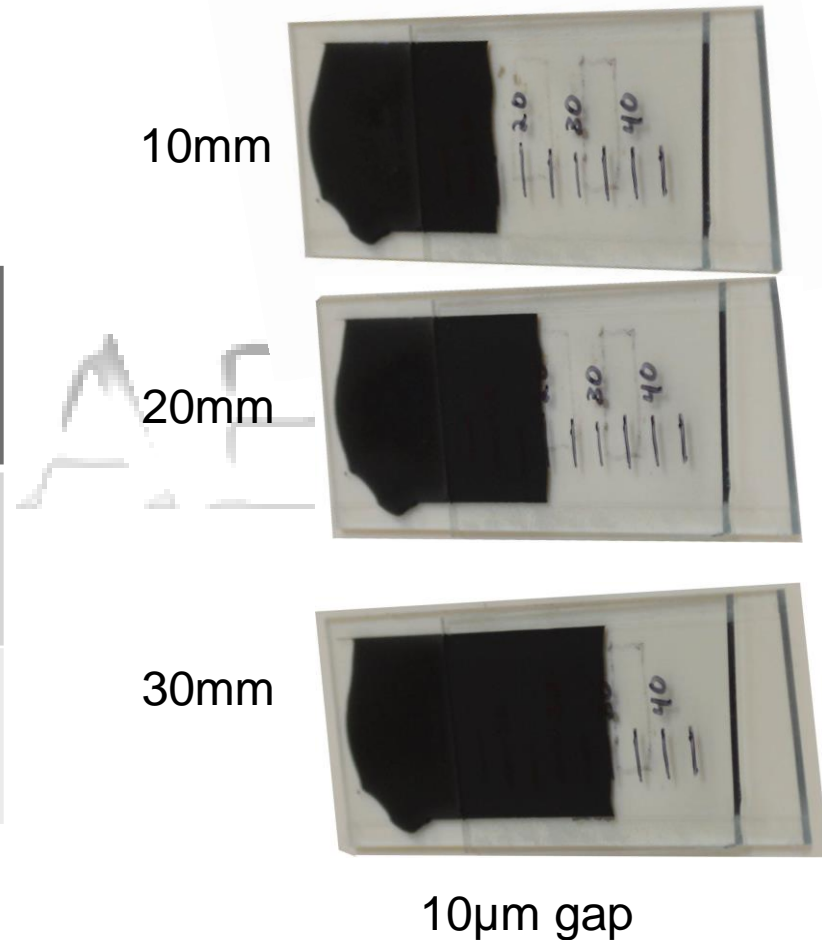
Fast Flow

Good for small gap filling

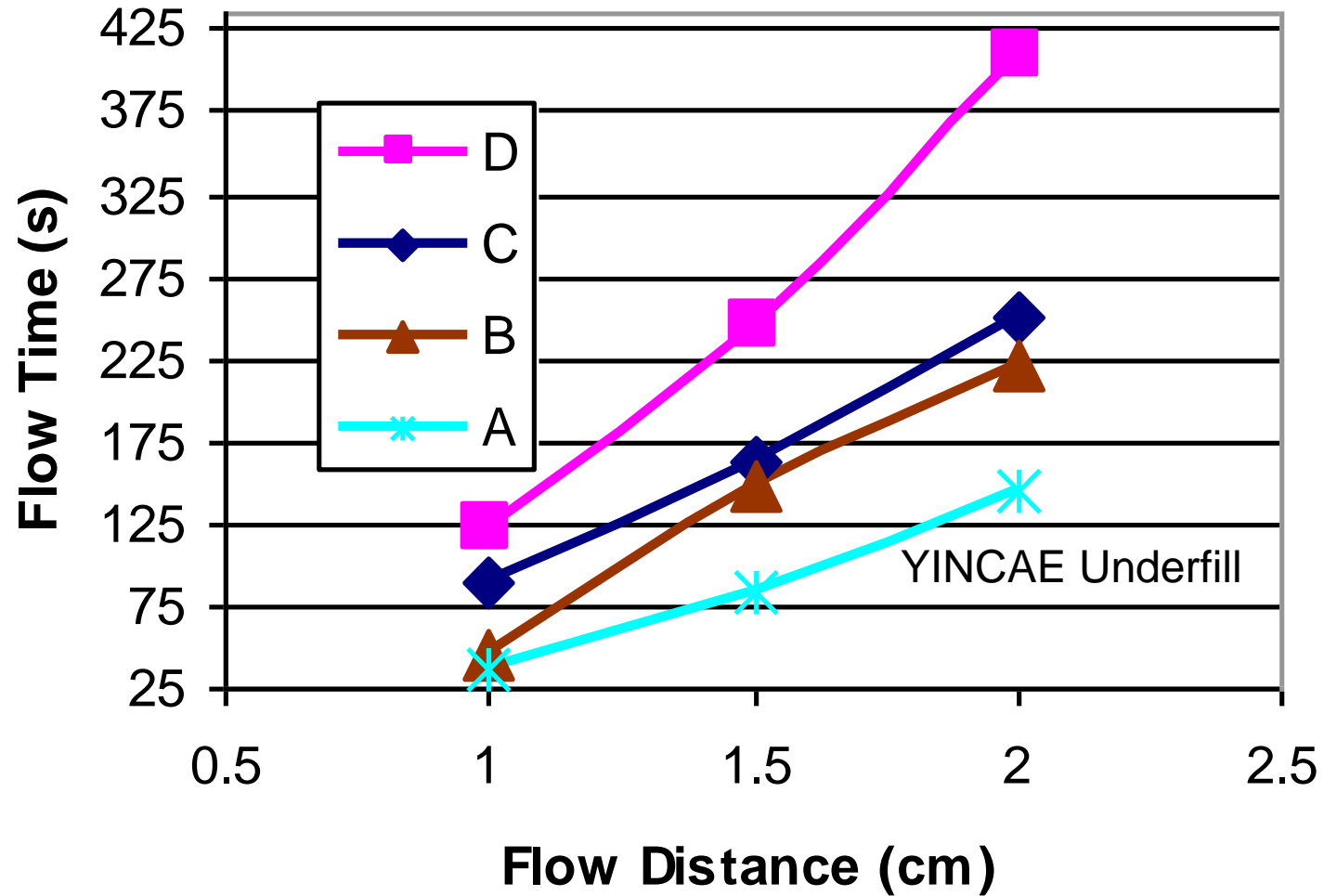
Viscosity: 10-12Pa.s

0.062Pa.s @ 110°C

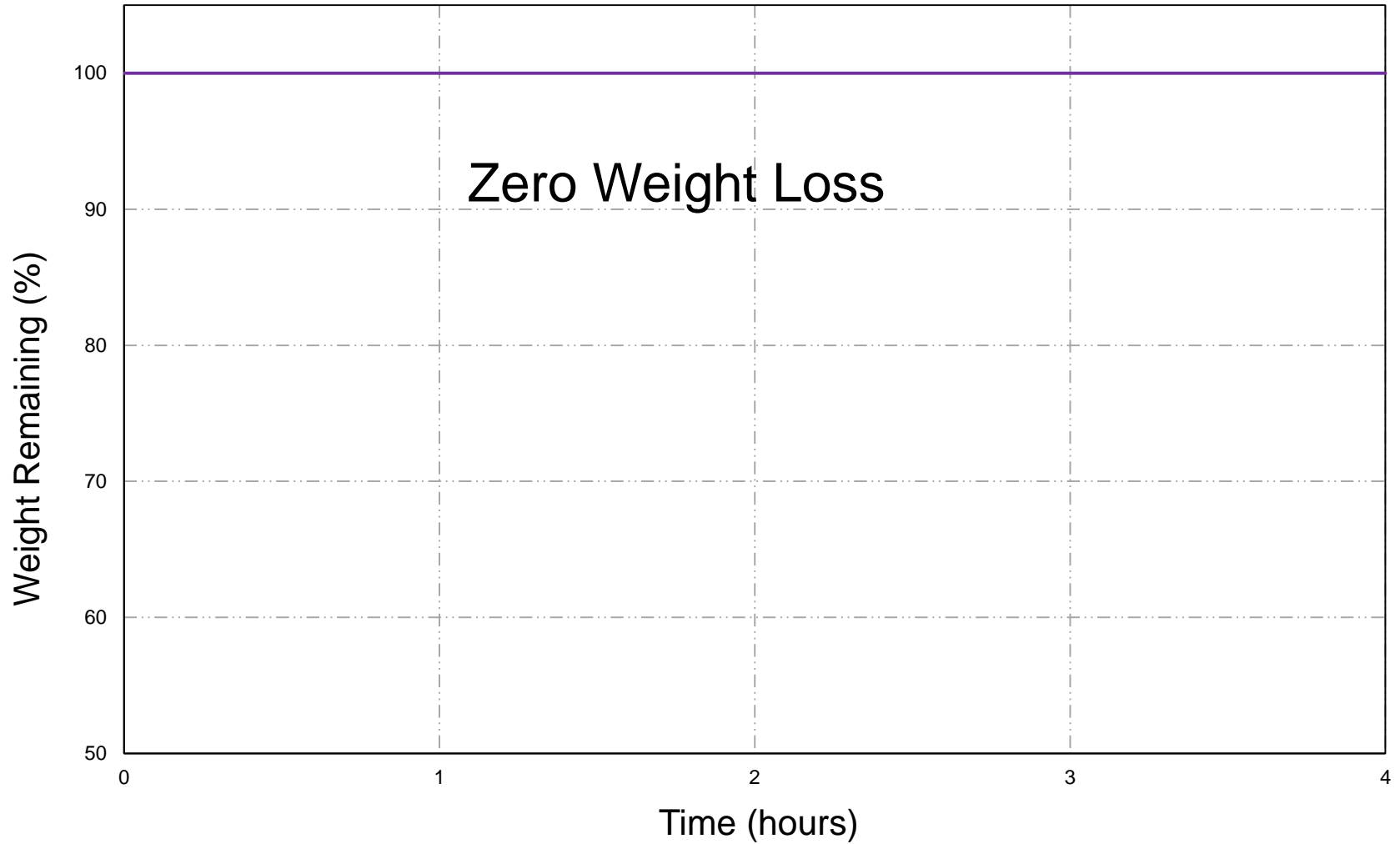
Gap (μm)	Distance (mm)	10	20	30
10	Flow time(s)	19	85	240
20	Flow time(s)	14	70	186



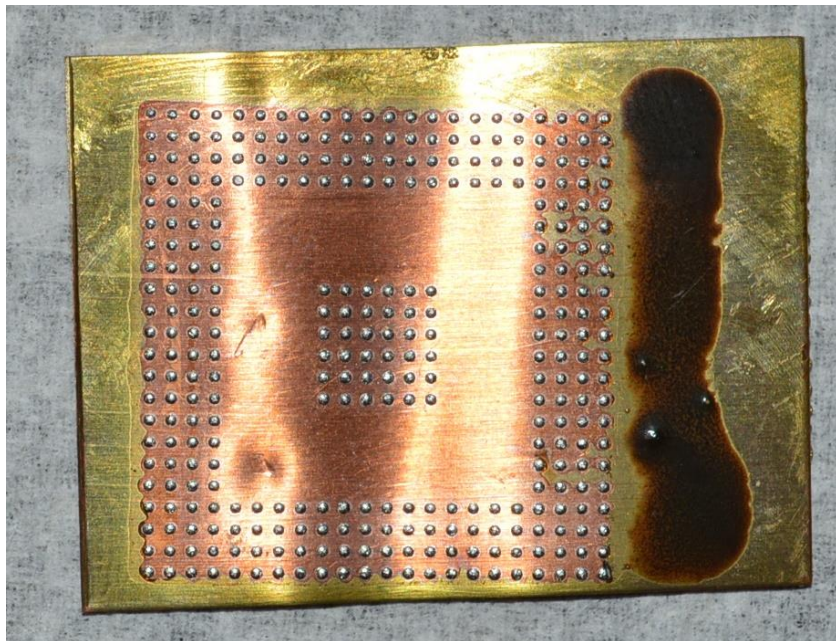
Flowability Comparison



Weight Loss

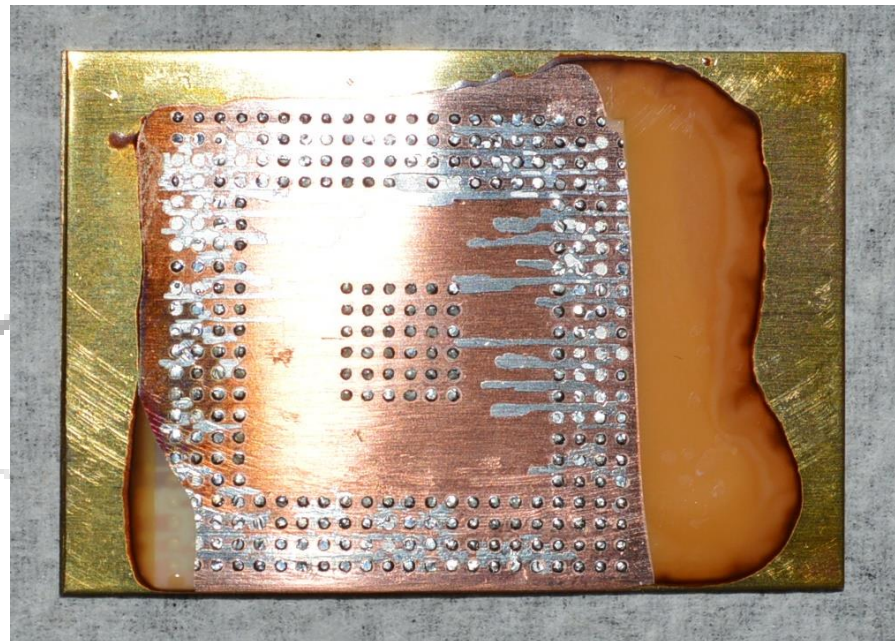


5x 260 °C Reflow Testing



YINCAE Underfill

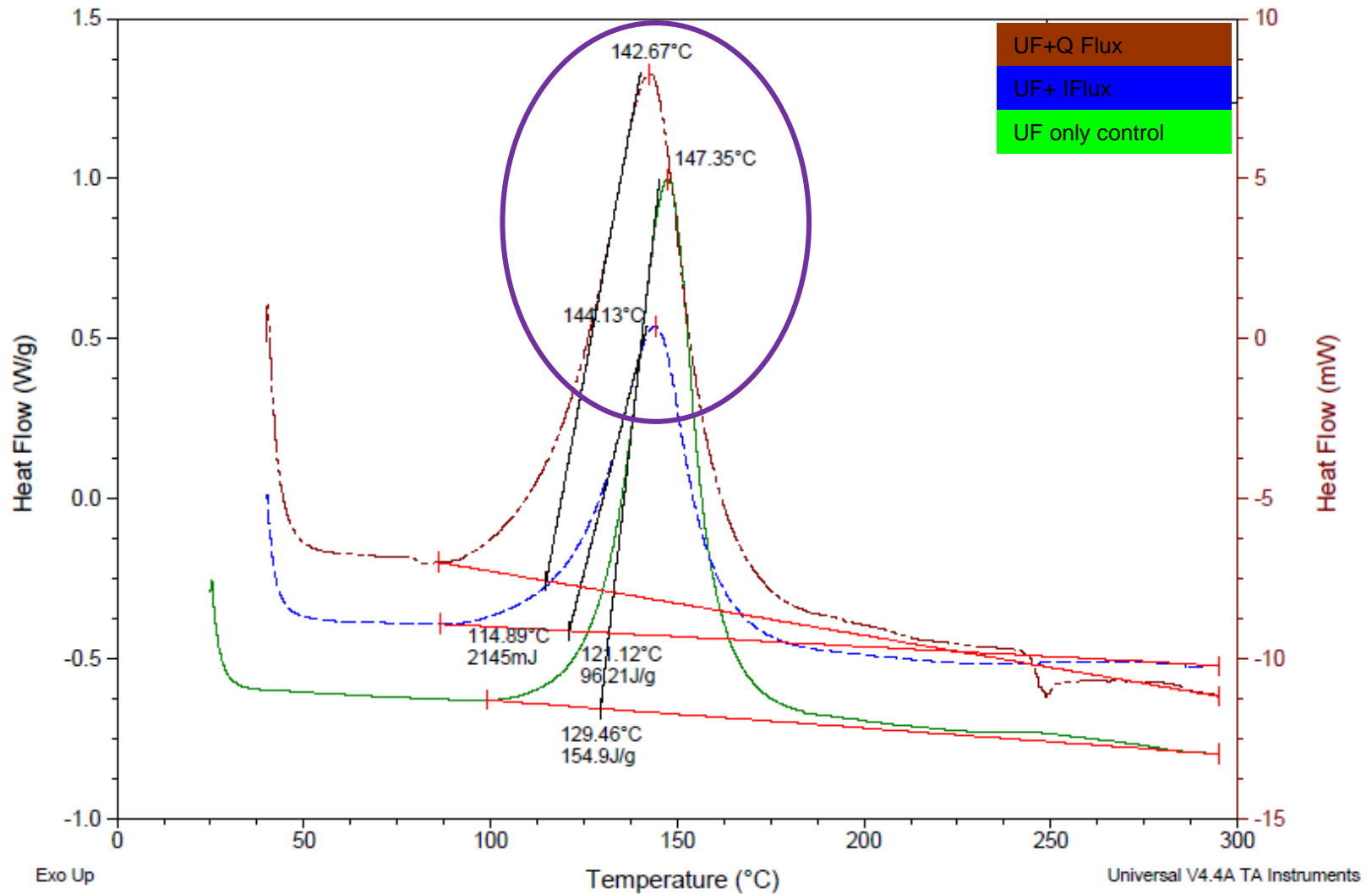
No delamination and
solder extrusion



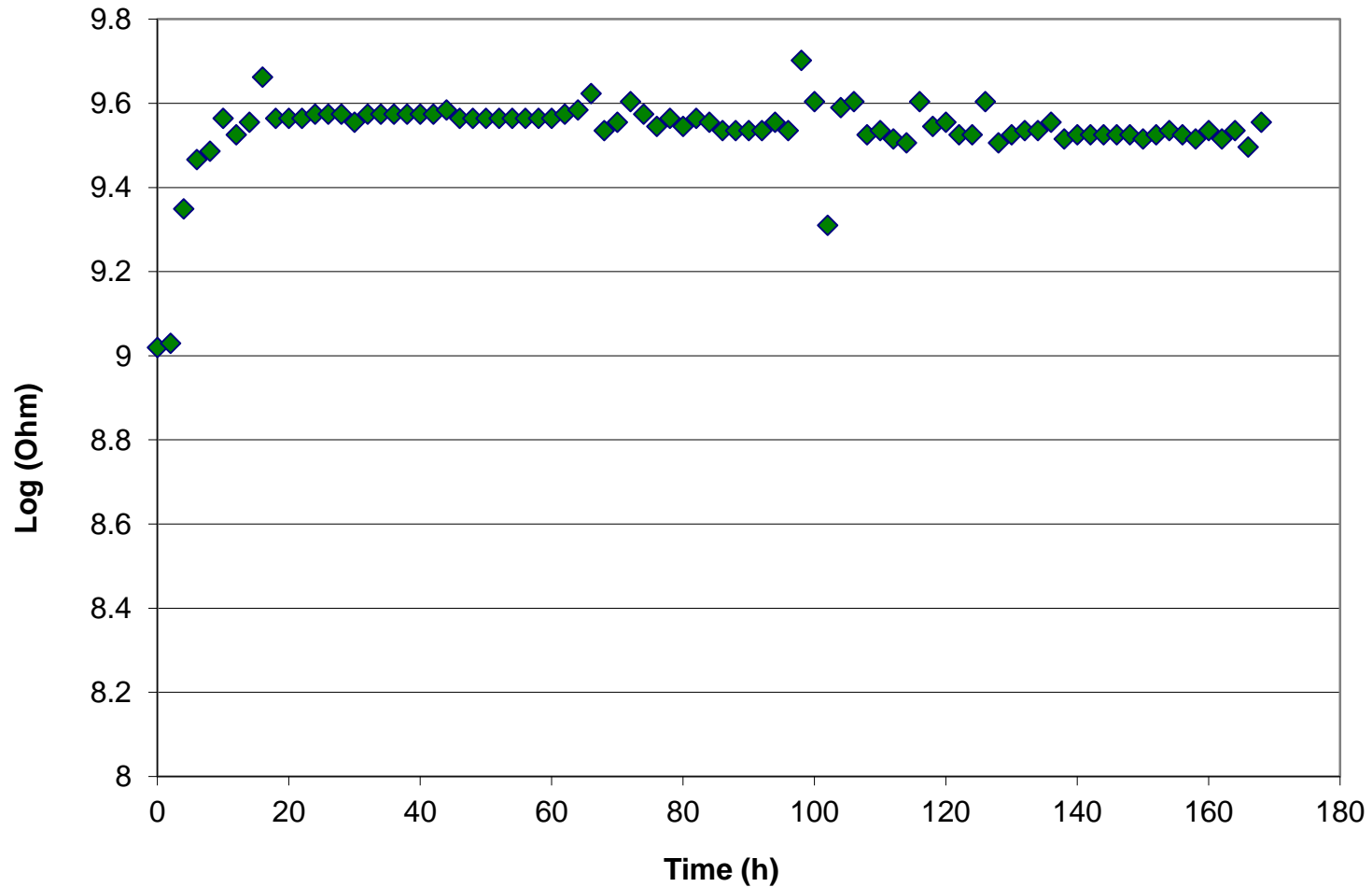
“ C ” underfill

Delamination and
Solder Extrusion

Compatibility With Flux

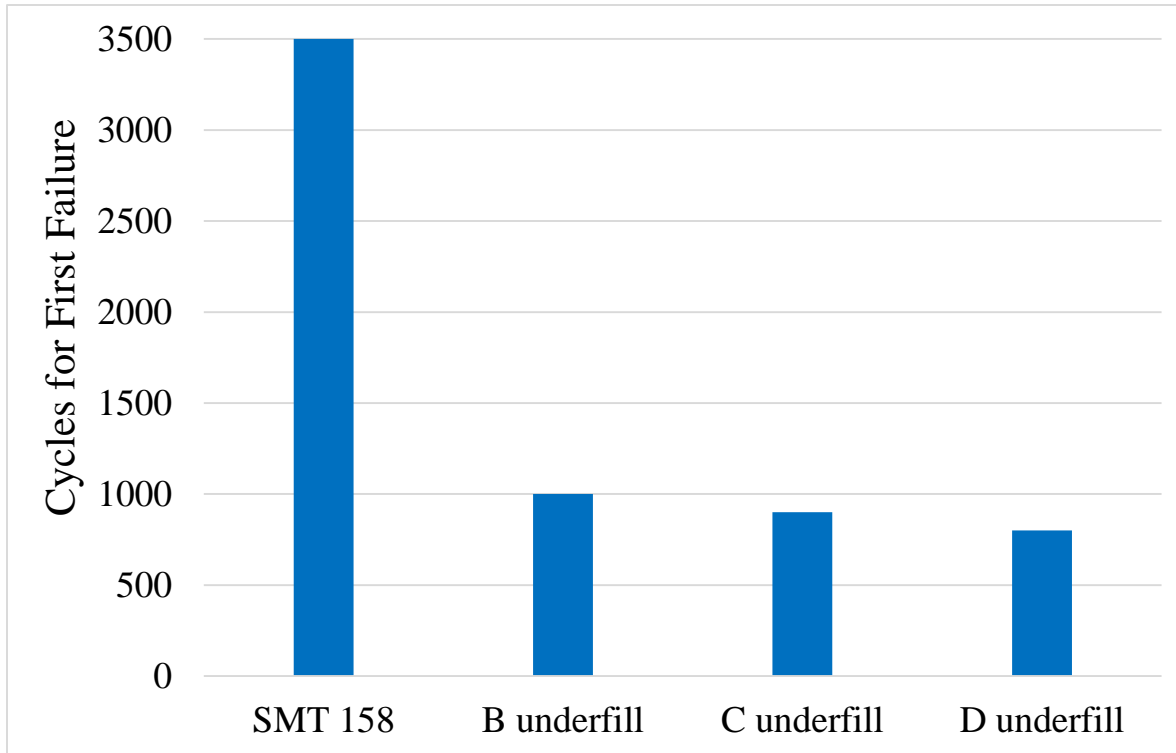


SIR Test



Temperature/RH: 85C/ 85 %

Thermal Cycling Performance



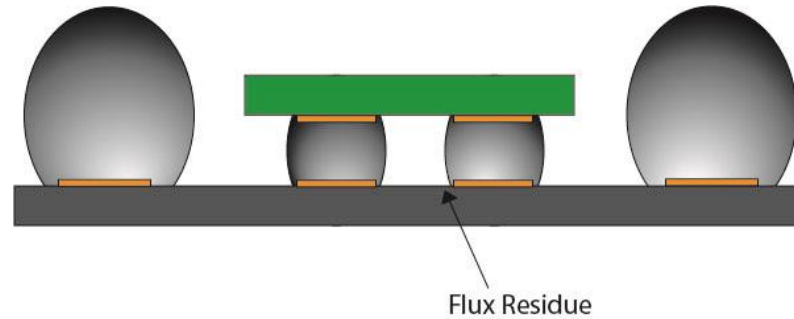
Thermal cycling conditions:
-45 ° C ~ 125 ° C;
One hour per cycle.

Underfill thermal cycling performance from best to worst:

YINCAE Underfill
B underfill
C underfill
D underfill

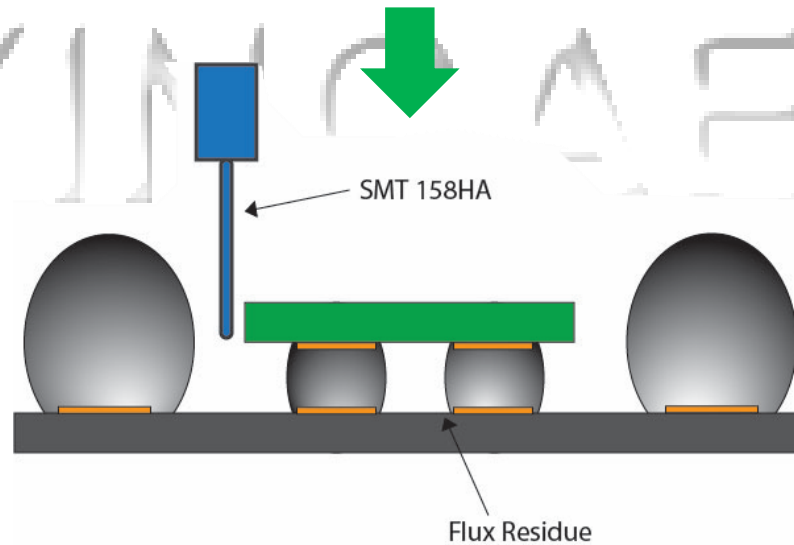
YINCAE Underfill: Tg 160-200 °C , CTE 22ppm/K

Discussion



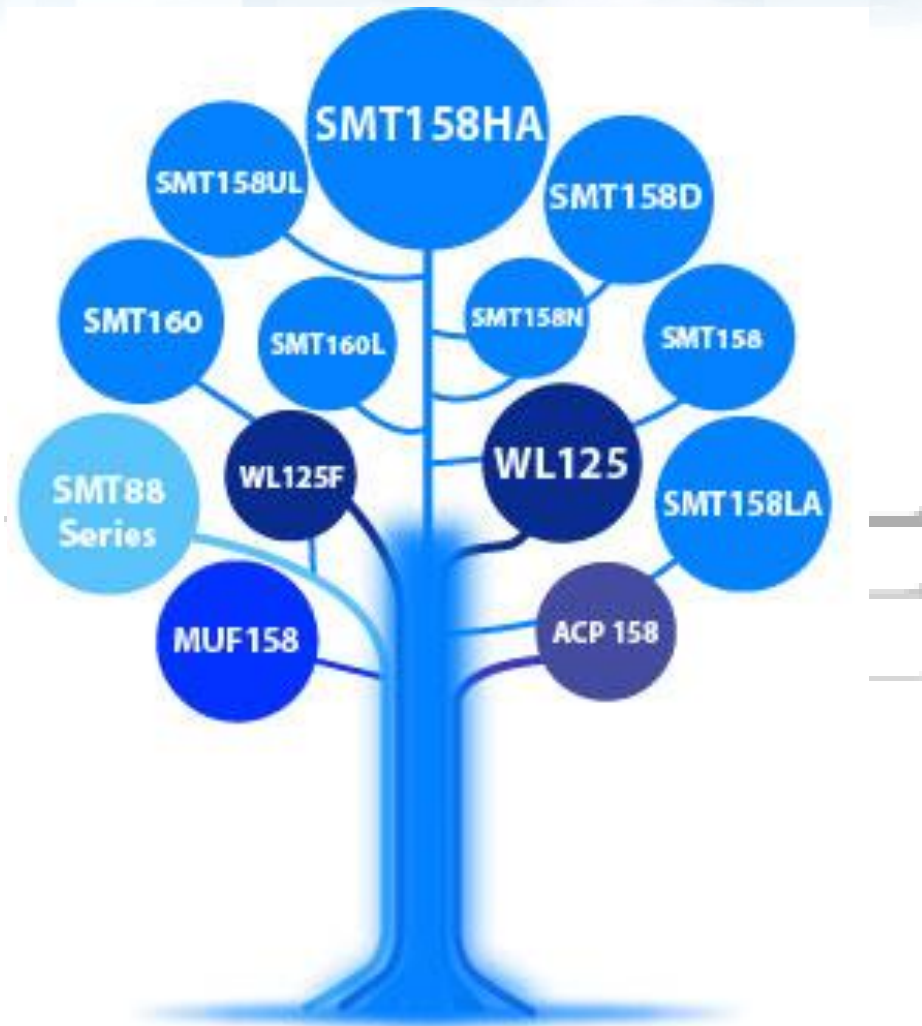
Any Issues?

YINCAE Solutions



Simplified underfilling process in wafer-level

YINCAE Underfill Solutions



Underfill Materials

Conclusion

- YINCAE has successfully developed a unique zero outgassing flux compatible underfill with high Tg and low CTE. The benefits are:
 - Eliminates the need for plasma cleaning
 - Fully compatible with all flux residues
 - Withstands up to 5x 260 °C reflow

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Thank you

Please come to visit our
booth with any questions

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